



K888G4

2U2P HPC Server System

Highlights

- Intel[®] Xeon[®] Processors Scalable Family
- Efficient Dual-Sockets System Supporting onboard 10GbE Network
- Optimum Storage Density
- Reducing OPEX
- Flexible and Scalable I/O Options
- Optimized Serviceability



K888G4 series servers target HPC (high performance computing), storage and general purpose usage with twenty-four DIMM capacity (up to 3TB with 128GB DIMMs) and expandability up to six PCIe cards. The series are optimized for great density and scalability in a simple 2U enclosure with tool-less storage drives and hotswappable fan modules, applicable for a wide variety of virtualization solutions, big data analysis scenarios, among others that demand better flexibility, higher performance and greater storage capability.

High Performance

The new generation Intel[®] Xeon[®] Processor Scalable Family are based on Intel 14nm process technology that lay new foundation of scalability offering optimized workload for synergy across compute, network and storage, with up to 3.9x higher virtualized workload throughput and number of VMs, a great boost in performance, security, agility and efficiency, catering to wide range of key workloads.

Front View



Rear View





Great Density and Scalability

Adopting Intel[®]C622 chipset, supporting dual Intel[®] Xeon[®] Processor Scalable Family and up to 3TB of DDR4 memory. K888G4 series host four PCIe x16 lanes, enabling expansion of up to six PCIe cards with riser boards, and support the latest Intel[®] technologies, such as Intel[®] Optane[™] Persistent Memory which is ready with platform codenamed Cascade Lake, etc.

Flexible Network Configuration

Offering dual 10G SFP+ on board NIC (Network Interface Controller), and a variety of network choices through OCP NIC mezzanine cards, ranging from 10G Ethernet to 100G (optical or Base-T, compatible with OCP 2.0), the highspeed performance and IO flexibility are realized, catering to suitable demands of different application procedures.

About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

K888G4 HPC Server System

Positioning	Standard/Mainstream
Form Factor	2U1N Rack-Mounted W x H x D: 447 x 87 x 450mm (17.60" x 3.43" x17.72")
Processor	Dual Socket;Intel [®] Xeon [®] Processor Scalable Family
Memory	24x DDR4 DIMM slot
Chipset	Intel [®] C620 series (C622), supporting 10GbE
Disk Drive Bay	Front primary bays: Option1: 12x 3.5" SAS/SATA (including optional 4x NVMe) hot-plug drive Option2: 24x 2.5" SAS/SATA (including optional 4x NVMe) hot-plug drive Optional 4x U.2 or M.2 NVMe drive Rear SSD bays:2x 2.5" SATA hot-plug drive
Expansion Slot	Option1: 3x PCIE Gen3 x16 (Low Profile) Option2: 4x PCIE Gen3 x8 (FHFL), 2x PCIE Gen3 x8 (Low Profile) 1x PCIe Gen3 OCP 2.0 A+B NIC Mezz 1x Inventec Storage mezz
Network Controller	Onboard:Dual 10G SFP+Supporting 10GbE/25GbE/100GbE Mezz and Standard PCIe card Inventec network OCP mezz card options: Option1: NIC-I350-1GDC (Dual port 1Gb RJ-45) Option2: NIC-I599-10GD (Dual port 10Gb SFP+) Option3: NIC-I540-10GDC (Dual port 10Gb RJ-45)
Storage Controller	Onboard:12x SATA3 6Gb/s port Inventec storage mezz card options Option1: SAS3-3008-8i (12Gb/s) Option2: SAS3-3216-16i (12Gb/s) Option3: SAS3-3224-24i (12Gb/s) Option4: SAS3-3324-24i (12Gb/s, RAID)
System Management	IPMI 2.0 compliant+ KVM with Dedicated LAN
ТРМ	2.0
Power Supply	1+1 redundancy Option1: 1600W (220V) Platinum Option2: 800W (110V) Platinum
Fan	N+1 redundancy , 6x 6038 hot-swap fan
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